Display Elektronik GmbH

DATA SHEET

LCD-MODULE

DEM 128064R FGH-PW

Product Specification

Ver.: 0

Revision History

| VERSION | DATE | REVISED PAGE NO. | Note |
|---------|------------|------------------|-------------|
| 0 | 04.11.2020 | | First Issue |

Contents

- 1. General Specification
- 2. Interface Pin Function
- 3. Contour Drawing
- 4. Optical Characteristics
- 5. Absolute Maximum Ratings
- 6. Electrical Characteristics
- 7. Backlight Information
- 8. Reliability
- 9. Inspection specification
- 10. Precautions in use of LCD Modules
- 11. Material List of Components for RoHs
- 12. Recommendable Storage

1. General Specification

The Features is described as follow:

n Module Dimension: 60.10 x 44.50 x 5.01(Max)

n View Area: 54.6 x 32.0

n Active Area: 49.89 x 27.49

n Dot Size: 0.36 x 0.40

n Dot Pitch: 0.39 x 0.43

n Number of Dots: 128 x 64

n LCD Type: FSTN Positive Transflective (Anti-Glare)

n Drive Method: 1/65 DUTY, 1/9BIAS

n View Direction: 6 o'clock

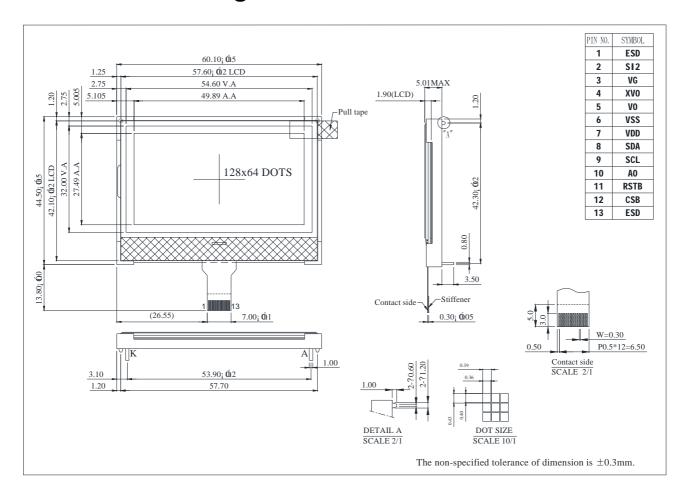
n Backlight Type: LED, White

n IC: ST7567A (SPI & I2C)

2. Interface Pin Function

| Pin No. | Symbol | | | Description | | | | |
|---------|--------|------------------------|--|--|--------------------------|--|--|--|
| 1 | ESD | ESD | ESD | | | | | |
| | | These pins | hese pins select the display duty and bias of ST7567A. | | | | | |
| | | SEL2 | SEL1 | Duty | Bias | | | |
| 2 | SI2 | "L" | "L" | 1/65 | 1/9 or 1/7 | | | |
| | OIZ | "L" | "H" | 1/49 | 1/8 or 1/6 | | | |
| | | "H" | "L" | 1/33 | 1/6 or 1/5 | | | |
| | | "H" | "H" | 1/55 | 1/8 or 1/6 | | | |
| 3 | VG | VG is the Lo | CD driving | voltage for segmer | nt circuits | | | |
| 4 | XV0 | XV0 is the L | _CD driving | voltage for commo | on circuits at positive | | | |
| 5 | V0 | V0 is the L0 | CD driving v | oltage for commor | n circuits at negative | | | |
| 6 | VSS | GROUND | GROUND | | | | | |
| 7 | VDD | POWER | | | | | | |
| 8 | SDA | | | ted together as SD | | | | |
| 9 | SCL | ¬D[4:7]=(1,1, VSSL. | ,1,1): ID Pir | n. D[4:7] should fix | to "H" or "L" by VDDH or | | | |
| 10 | A0 | A0="H" : Ind | dicates that | the access is relate signals on D[7:0] a signals on D[7:0] a | • • | | | |
| 11 | RSTB | | Hardware reset input pin. When RSTB is "L", internal initialization s executed and the internal registers will be initialized. | | | | | |
| 12 | CSB | Chip select "L". | input pin. lı | nterface access is | enabled when CSB is | | | |
| 13 | ESD | ESD | | | | | | |

3. Contour Drawing

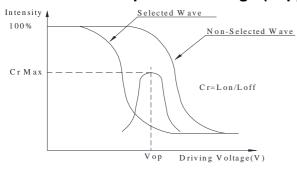


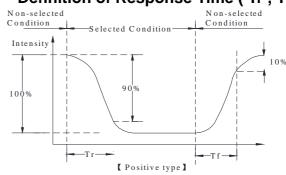
4. Optical Characteristics

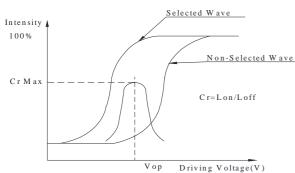
| Item | Symbol | Condition | Min | Тур | Max | Unit |
|----------------|--------|-----------|-----|-----|------------------------|---------|
| | θ | CR≧2 | - | - | 25 | ψ= 180° |
| Vienn Amerika | θ | CR≧2 | - | - | 45 | ψ= 0° |
| View Angle | θ | CR≧2 | - | - | 35 | ψ= 90° |
| | θ | CR≧2 | - | - | 25 ψ= 180° 45 ψ= 0° | |
| Contrast Ratio | CR | - | 3.0 | - | - | - |
| Danis Time | T rise | - | - | - | 250 | ms |
| Response Time | T fall | - | - | - | 250 | ms |

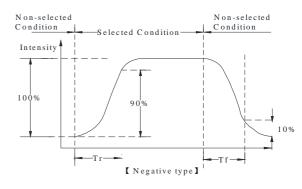
Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)







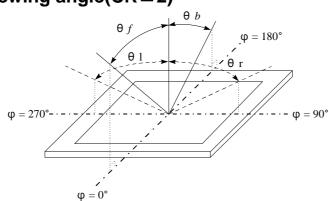


Conditions:

Operating Voltage : Vop $Viewing Angle(\theta, \phi) : 0^{\circ}, 0^{\circ}$

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

Definition of viewing angle(CR≥2)



5. Absolute Maximum Ratings

| Item | Symbol | Min | Тур | Max | Unit |
|------------------------------|----------------------|------|-----|----------------------|------|
| Operating Temperature | Тор | -20 | - | +70 | °C |
| Storage Temperature | Тѕт | -30 | - | +80 | °C |
| Input Voltage | Vı | -0.3 | - | V _{DD} +0.3 | V |
| Digital Power Supply Voltage | V _{DD} -Vss | -0.3 | - | 4.0 | V |
| LCD Power Supply Voltage | V0-XV0 | -0.3 | - | 18.0 | V |

6. Electrical Characteristics

| Item | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------------|----------------------|--------------------------|---------------|---------------|--------------------|-------------|
| Supply Voltage For Logic | V _{DD} -Vss | - | 2.9 | 3.0 | 3.1 | V |
| Supply Voltage For LCD *Note | Vop | Ta=-20°C Ta=25°C Ta=70°C | - 9.3 - | - 9.5 - | 9.7 | V V V |
| Input High Volt. | Vıн | - | 0.7VDD | - | V _{DD} | V |
| Input Low Volt. | VIL | - | Vss | - | 0.3V _{DD} | V |
| Supply Current | I _{DD} | - | | | 2.0 | mA |

Please kindly consider to design the Vop to be adjustable while programing the software to match LCD contrast tolerance

7. Backlight Information

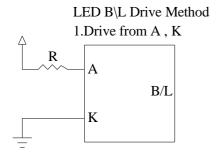
Specification

| PARAMETER | SYMBOL | MIN | TYP | MAX | UNIT | TEST CONDITION |
|--|--------|-----|-----|-----|-------------------|--|
| Supply Current | ILED | - | 64 | 80 | mA | V=3.5V |
| Supply Voltage | V | 3.4 | 3.5 | 3.6 | V | |
| Reverse Voltage | VR | - | - | 5 | V | - |
| Luminance (Without LCD) | IV | 650 | 820 | - | CD/M ² | ILED=64mA |
| LED Life Time (For Reference only) | - | - | 50K | - | | ILED□64mA 25□,50-60%RH, (Note 1) |
| Color | White | | | | | |

Note: The LED of B/L is drive by current only; driving voltage is only for reference

To make driving current in safety area (waste current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.



8. Reliability

Content of Reliability Test (Wide Temperature, -20°C ~ 70°C)

| | Environmental Test | | |
|---------------------------------------|---|---|------|
| Test Item | Content of Test | Test Condition | Note |
| High Temperature Storage | Endurance test applying the high storage temperature for a long time. | 200hrs | 2 |
| Low Temperature Storage | Endurance test applying the low storage temperature for a long time. | -30°C 200hrs | 1,2 |
| High Temperature Operation | Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time. | 70°C 200hrs | |
| Low Temperature Operation | Endurance test applying the electric stress under low temperature for a long time. | -20°C 200hrs | 1 |
| High Temperature/ Humidity Storage | The module should be allowed to stand at 60□,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature. | 60°C,90%RH 96hrs | 1,2 |
| Thermal Shock Resistance | The sample should be allowed stand the following 10 cycles of operation -20 25 70 30min 5min 30min 1 cycle | -20°C/70°C 10 cycles | |
| Vibration Test | Endurance test applying the vibration during transportation and using. | Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes | 3 |
| Static Electricity Test | Endurance test applying the electric stress to the terminal. | VS=±600V(contact), ±800v(air), RS=330Ω CS=150pF 10 times | |

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

9. Inspection specification

| NO | Item | | | Criterion | | AQL | | |
|----|---|--|---|--|--|-----|--|--|
| 01 | Electrical Testing | defect. 1.2 Missing characters of the characters | 1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect. | | | | | |
| 02 | Black or white spots on LCD (display only) | three white or 2.2 Densely space 3mm | 2.1 White and black spots on display ≦0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within | | | | | |
| 03 | LCD black spots, white spots, contamination (non-display) | 3.1 Round type : A $\Phi = (x + y) / 2$ | | SIZE Φ≦0.10 0.10 < Φ≦0.20 0.20 < Φ≦0.25 0.25 < Φ | Acceptable Q TY Accept no dense 2 1 0 | 2.5 | | |
| | | 3.2 Line type : (As | | | | | | |
| | | | Length | Width W≦0.02 | Acceptable Q TY Accept no dense | | | |
| | | | L≦3.0 | 0.02 < W≦0.03 | | 2.5 | | |
| | | | L≦2.5 | 0.03 < W≦0.05 | 2 | | | |

| | | → L H— | 0.05 < W | As round type | |
|----|-----------|---|---------------|-----------------|-----|
| | | | | | |
| | | If bubbles are visible, | Size Φ | Acceptable Q TY | |
| | | judge using black spot specifications, not easy | Ф≦0.20 | Accept no dense | |
| 04 | Polarizer | Polarizer to find, must check in specify direction. | 0.20 < Φ≦0.50 | 3 | 2.5 |
| | bubbles | | 0.50 < Φ≦1.00 | 2 | |
| | | | 1.00 < Ф | 0 | |
| | | | Total Q TY | 3 | |

| NO | Item | | Criterion | | AQL |
|----|------------------|-------------------------------------|--|----------------------------|-----|
| 05 | Scratches | Follow NO.3 LCD black | spots, white spots, con | tamination | |
| 05 | | Symbols Define: x: Chip length y: 0 | spots, white spots, con Chip width z: Chip to Glass thickness a: LCE | thickness O side length | |
| 06 | Chipped glass | Z≦1/2t | Not over viewing area Not exceed 1/3k | x≦1/8a x≦1/8a | 2.5 |
| | | z: Chip thickness | y: Chip width Not over viewing | x: Chip length | |
| | | Z≦1/2t 1/2t < z≦2t | area Not exceed 1/3k | x≦1/8a x≦1/8a | |
| | | ⊙If there are 2 or more | chips, x is the total leng | th of each chip. | |

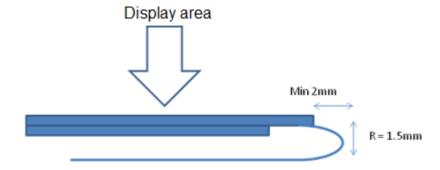
| NO | Item | | Criterion | | AQL |
|----|----------------|---|------------------------|----------------------|-----|
| | | Symbols: x: Chip length y: Chip k: Seal width t: Glass L: Electrode pad length 6.2 Protrusion over terminal 6.2.1 Chip on electrode pad | s thickness a: LCD s | | |
| | | y: Chip width | x: Chip length | z: Chip thickness | |
| | | y≦0.5mm | x≦1/8a | 0 < z≦t | |
| | | 6.2.2 Non-conductive portio | n: | | |
| 06 | Glass crack | y Z | y | | 2.5 |
| | | y: Chip width | x: Chip length | z: Chip thickness | |
| | | y≦ L | x≦1/8a | 0 < z≦t | |
| | | ⊙If the chipped area t | | | |
| | | must remain and be specifications. | e inspected according | to electrode termina | ıl |
| | | ⊙If the product will be | e heat sealed by the c | ustomer, the alignme | ent |
| | | mark not be damag 6.2.3 Substrate protuberand | | | |
| | | X | y: width | x: length | |
| | | | - | | |
| | | у | y≦1/3L | x≦a | |
| | | | | | |

| NO | Item | Criterion | AQL |
|----|-----------------------|--|---|
| 07 | Cracked glass | The LCD with extensive crack is not acceptable. | 2.5 |
| 08 | Backlight elements | 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. | 0.65 2.5 0.65 |
| 09 | Bezel | 9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications. | 2.5 0.65 |
| 10 | PCB、COB | 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB | 2.5 2.5 0.65 2.5 0.65 2.5 2.5 |
| 11 | Soldering | 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. | 2.5 2.5 2.5 0.65 |

| NO | Item Criterion | | | | |
|-------|-----------------------|--|--|--|--|
| NO 12 | General appearance | 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. | 2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65 | | |
| | | 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 12.12 Visual defect outside of VA is not considered to be rejection. | 0.65 | | |

10. Precautions in use of LCD Modules

- (1)Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) Display Elektronik GmbH have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) Display Elektronik GmbH have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, Display Elektronik GmbH have the right to modify the version.)
- (10) To ensure the stability of the display screen, please apply screen saver after showing 30 mins of fixed display content.
- (11) The limitation of FPC bending



(12)Please heat up a little the tape sticking on the components when removing it; otherwise the components might be damaged.

11. Material List of Components for RoHs

1. Display Elektronik GmbH hereby declares that all of or part of products (with the mark "#"in code), including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

| Material | Cd | Pb | Hg | Cr6+ | PBB | PBDE | DEHP | BBP | DBP | DIBP | | | |
|--|-----|------|------|------|------|------|------|------|------|------|--|--|--|
| Limited | 100 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | 1000 | | | |
| Value | ppm | ppm | ppm | ppm | ppm | ppm | ppm | ppm | ppm | ppm | | | |
| Above limited value is set up according to RoHS. | | | | | | | | | | | | | |

- 2.Process for RoHS requirement: (only for RoHS inspection)
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering: 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp.: 235±5°C;

Recommended customer's soldering temp. of connector: 280°C, 3 seconds.

12. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.